

**900V, 30A, N-channel SiC power MOSFET**
**General Description:**

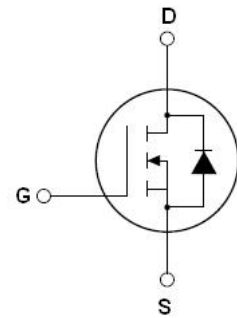
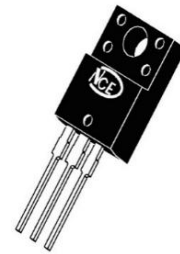
NCES090P100F is a SiC MOSFET that contributes to miniaturization and low power consumption of applications. This product achieves industry-leading low on-resistance without sacrificing short-circuit withstand time.

**Features**

- Low on-resistance
- Fast switching speed
- Fast reverse recovery
- Easy to parallel
- Simple to drive
- Pb-free lead plating ; RoHS compliant

**Application**

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives


**Schematic diagram**

**TO-220F-3L**
**Package Marking and Ordering Information**

Device	Device Package	Device Marking
NCES090P100F	TO-220F-3L	NCES090P100F

**Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	900	V
Gate-Source Voltage,max static voltage	V <sub>GS</sub>	-10 to +24	V
Gate-Source Voltage,max transient voltage (Note 1)	V <sub>GS</sub>	-11 to +26	V
Drain Current-Continuous (Note 2)	I <sub>D</sub>	30	A
Drain Current-Continuous(T <sub>c</sub> =100°C)	I <sub>D</sub> (100°C)	21	A
Pulsed Drain Current (Note 3)	I <sub>DM</sub>	75	A
Maximum Power Dissipation	P <sub>D</sub>	T <sub>vj</sub> = 25°C	32
		T <sub>vj</sub> = 100°C	16
Recommended turn-on gate - source drive voltage	V <sub>GS_on</sub>	+15 to +18	V
Recommended turn-off gate - source drive voltage	V <sub>GS_off</sub>	-4 to 0	V
Virtual junction temperature	T <sub>vj</sub>	175	°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	°C

**Thermal Characteristic**

Symbol	Parameter	Value	Units
R <sub>θJC</sub>	Thermal Resistance, Junction to case	4.7	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to ambient	80	°C/W

**Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
<b>Off Characteristics</b>							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =100μA	900			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =900V, V <sub>GS</sub> =0V	T <sub>vj</sub> = 25°C	1	80	μA	
			T <sub>vj</sub> = 175°C	2			
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =-10V / +24V, V <sub>DS</sub> =0V			±100	nA	
<b>On Characteristics</b> (Note 4)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =3mA	T <sub>vj</sub> = 25°C	1.9	3.0	4.8	V
			T <sub>vj</sub> = 175°C		2.1		
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =18V, I <sub>D</sub> =17A	T <sub>vj</sub> = 25°C	100	130	mΩ	
			T <sub>vj</sub> = 175°C	114			
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =15V, I <sub>D</sub> =17A	T <sub>vj</sub> = 25°C	138	180		
			T <sub>vj</sub> = 175°C	157			
Gate input resistance	R <sub>G</sub>	f=1MHZ, open drain		2.5		Ω	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =17A		7.5		S	
<b>Dynamic Characteristics</b> (Note 5)							
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V, f=1MHz		790		pF	
Output Capacitance	C <sub>oss</sub>			106		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			19.9		pF	
C <sub>oss</sub> stored energy	E <sub>oss</sub>			16.1		μJ	
Output charge	Q <sub>oss</sub>	Calculated by C <sub>oss</sub> (f)V <sub>DS</sub> @1MHz		78.9		nC	
Effective output capacitance, energy related	C <sub>o(er)</sub>	V <sub>DS</sub> =0-500V, V <sub>GS</sub> =0V		129		pF	
Effective output capacitance, time related	C <sub>o(tr)</sub>	I <sub>C</sub> =constant, V <sub>DS</sub> =0-500V, V <sub>GS</sub> =0V		158		pF	
<b>Switching Characteristics</b> (Note 5)							
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =500V, I <sub>D</sub> =17A, V <sub>GS</sub> =+18V / -3V, R <sub>G</sub> =2.7Ω, L=200μH		7.6		ns	
Turn-on Rise Time	t <sub>r</sub>			14.8		ns	
Turn-Off Delay Time	t <sub>d(off)</sub>			16.4		ns	
Turn-Off Fall Time	t <sub>f</sub>			6.7		ns	
Turn-on energy	E <sub>on</sub>	V <sub>DD</sub> =500V, I <sub>D</sub> =17A, V <sub>GS</sub> =+18V / -3V, R <sub>G</sub> =2.7Ω, L=200μH	T <sub>vj</sub> = 25°C	105		μJ	
			T <sub>vj</sub> = 175°C	145		μJ	
Turn-off energy	E <sub>off</sub>		T <sub>vj</sub> = 25°C	17.8		μJ	
			T <sub>vj</sub> = 175°C	22.4		μJ	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =500V, I <sub>D</sub> =17A, V <sub>GS</sub> =-3/18V		34		nC	
Gate-Source Charge	Q <sub>gs</sub>			8.6		nC	
Gate-Drain Charge	Q <sub>gd</sub>			11		nC	

**Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 4)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>SD</sub> =17A	T <sub>vj</sub> = 25°C		3.9	V
			T <sub>vj</sub> = 175°C		3.5	
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> =17A, V <sub>R</sub> =500V, di/dt = 2300A/μs (Note3)		9.8		ns
Reverse Recovery Charge	Q <sub>rr</sub>			107		nC
Peak reverse recovery current	I <sub>rrm</sub>			18.5		A

**Notes:**

1. t<sub>p</sub> < 500ns, D < 0.01
2. Repetitive Rating: Pulse width limited by maximum junction temperature.
3. PW ≤ 10μs, Duty cycle ≤ 1%
4. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
5. Guaranteed by design, not subject to production

Test Circuit

Fig.1-1 Gate Charge Measurement Circuit



Fig.1-2 Gate Charge Waveform

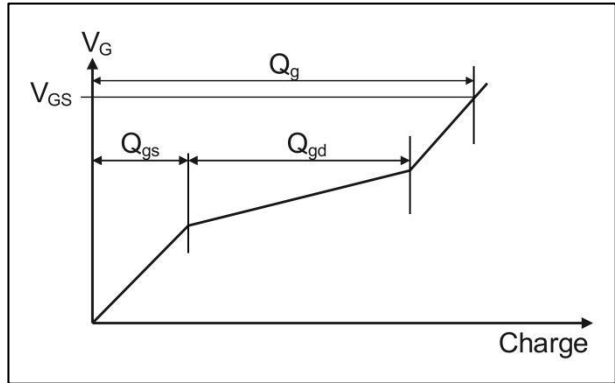


Fig.2-1 Switching Characteristics Measurement Circuit

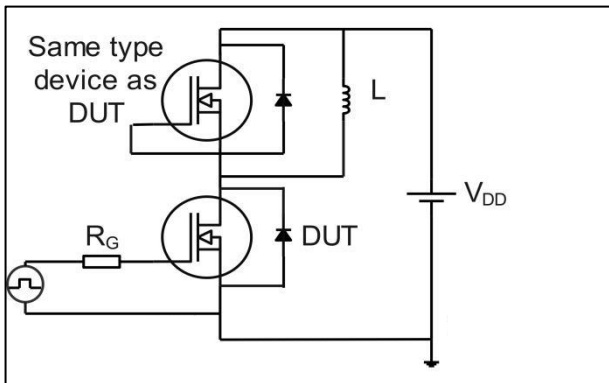
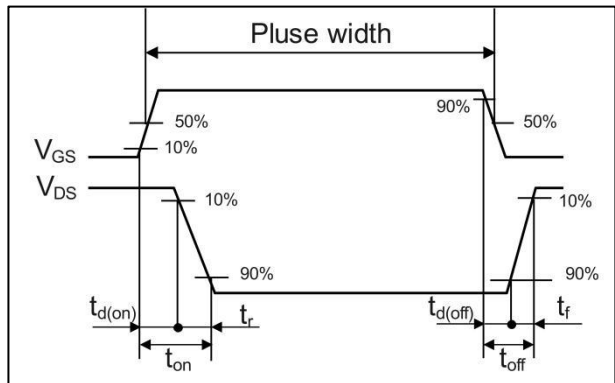


Fig.2-2 Waveforms for Switching Time



Typical Electrical and Thermal Characteristics

Fig.1 Power Dissipation Derating Curve

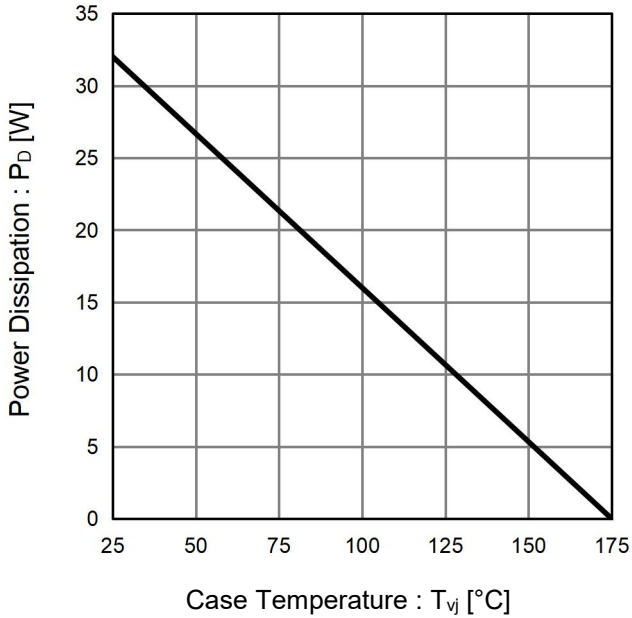


Fig.2 Maximum Safe Operating Area

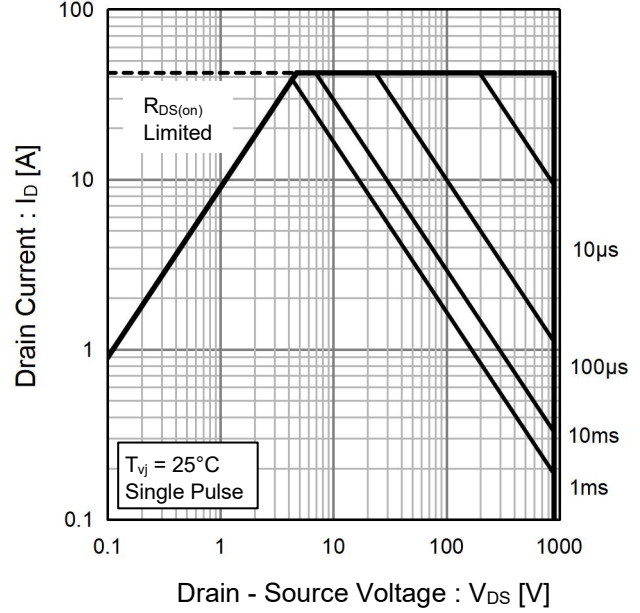


Fig.3 Typical Transient Thermal Impedance vs. Pulse Width

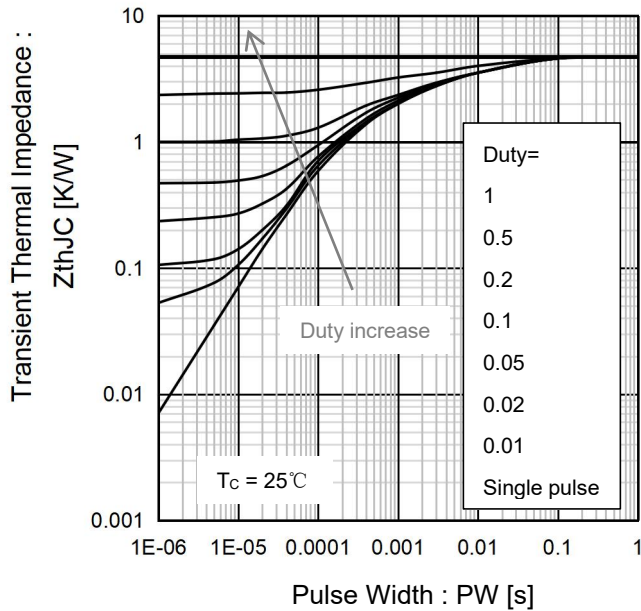


Fig.4  $T_{vj} = 25^{\circ}\text{C}$  Typical Output Characteristics

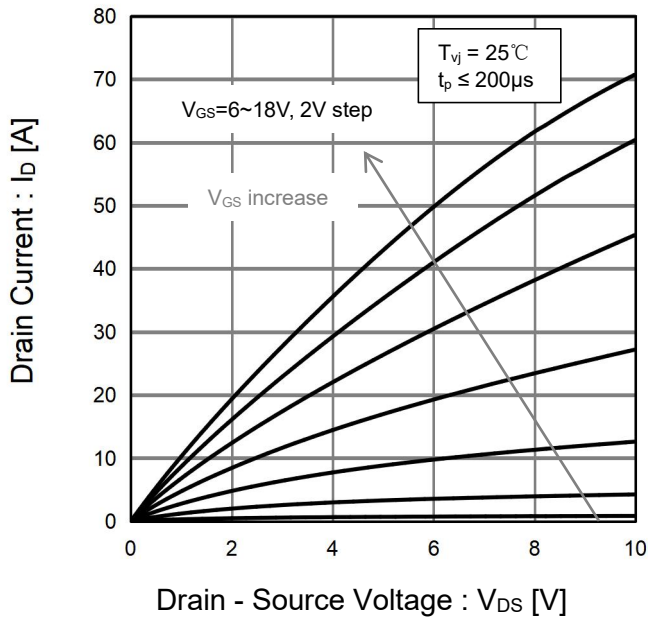


Fig.5  $T_{vj} = 25^{\circ}\text{C}$  3rd Quadrant Characteristics

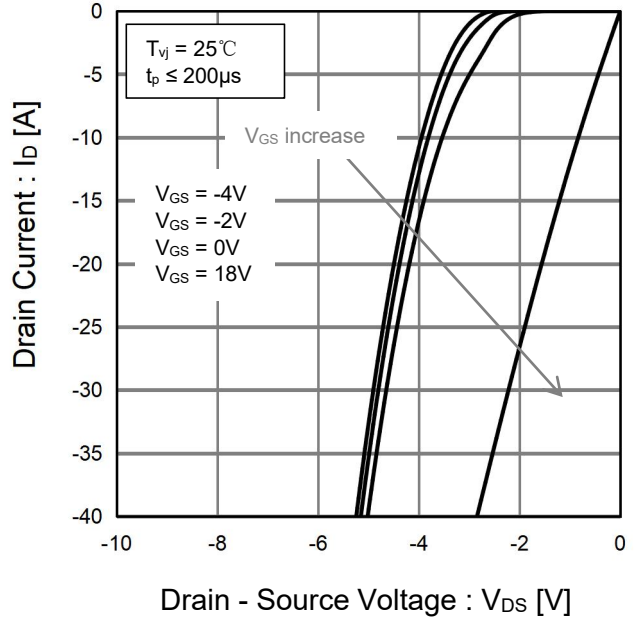


Fig.6  $T_{vj} = 175^{\circ}\text{C}$  Typical Output Characteristics

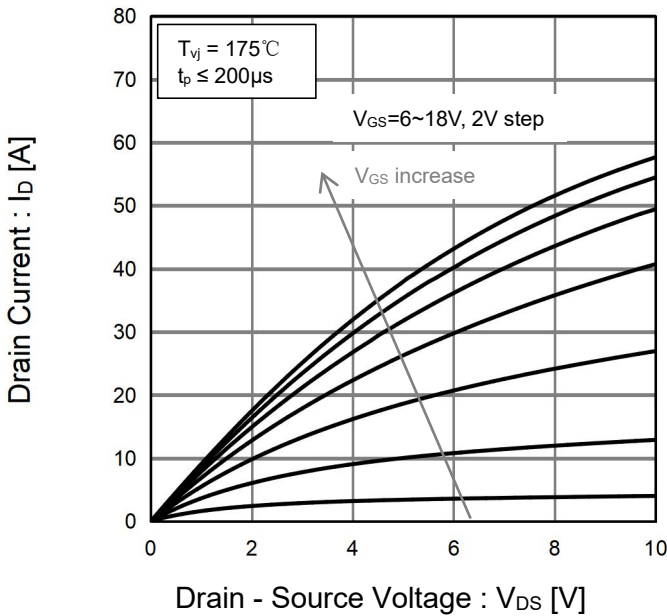


Fig.7  $T_{vj} = 175^{\circ}\text{C}$  3rd Quadrant Characteristics

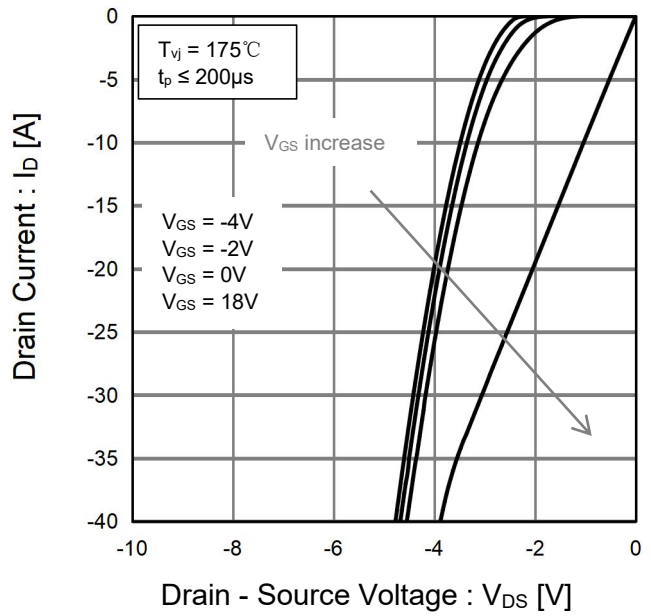


Fig.8 Typical Transfer Characteristics

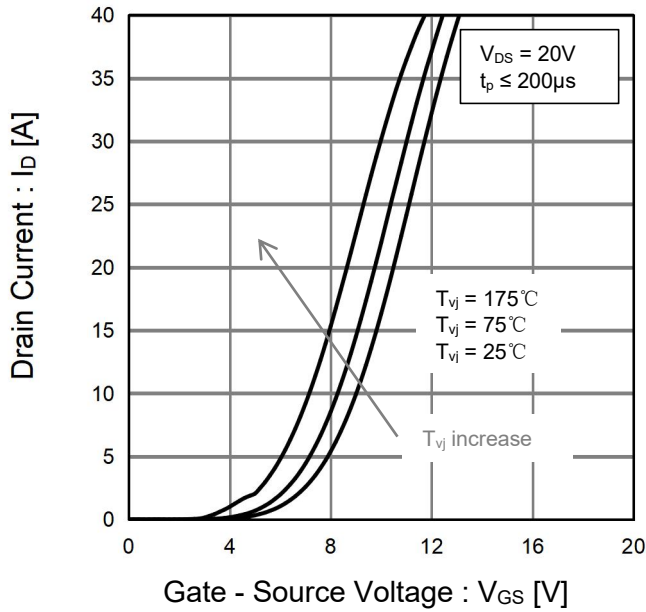


Fig.9 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

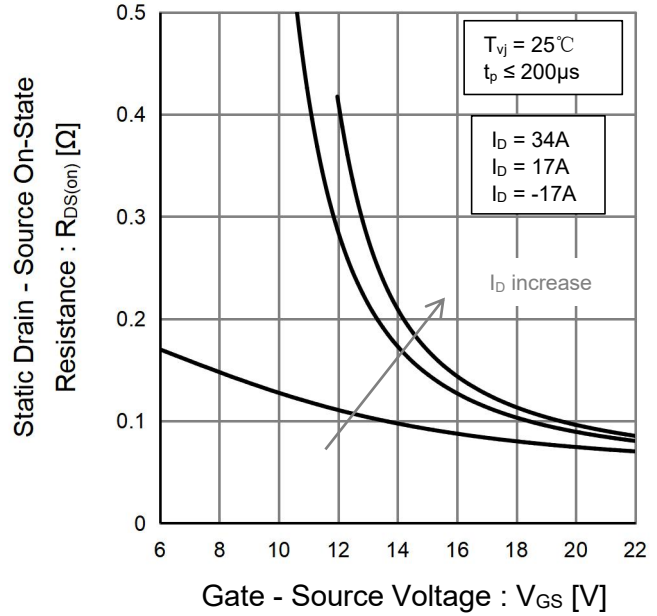


Fig.10 Static Drain - Source On - State Resistance vs. Drain Current

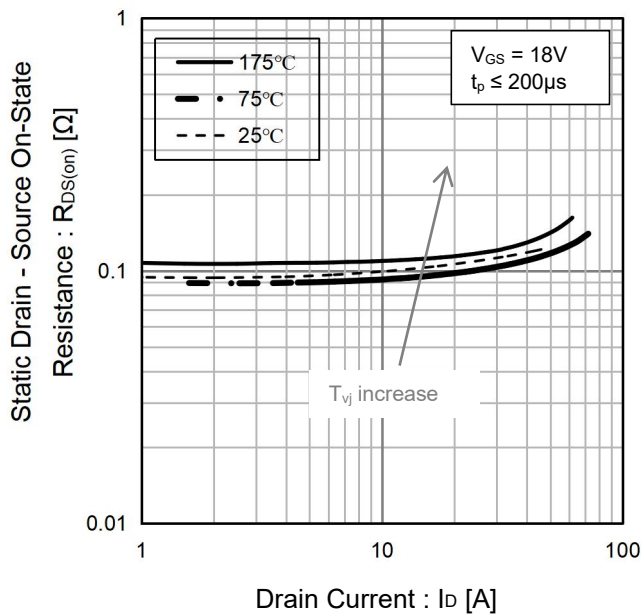


Fig.11 Static Drain - Source On - State Resistance vs. Virtual Junction Temperature

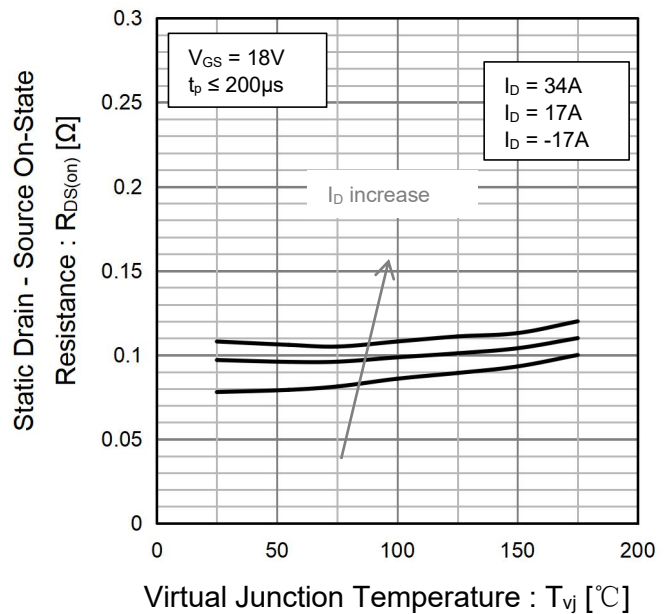


Fig.12 Body Diode Forward Voltage vs. Gate - Source Voltage

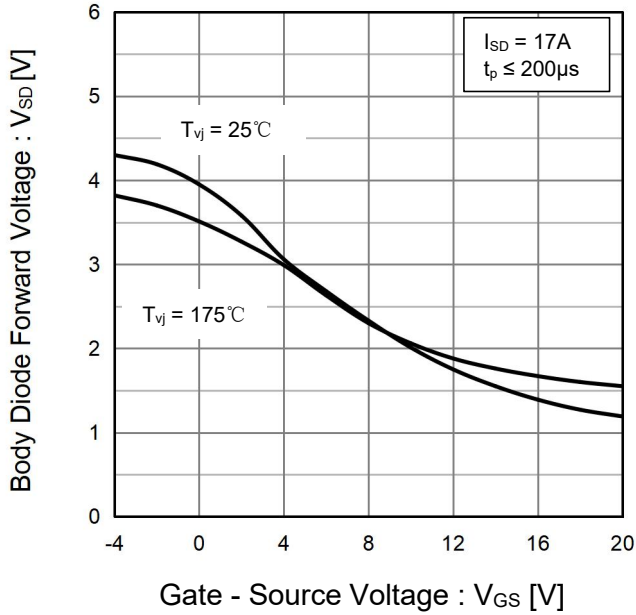


Fig.13 Gate Threshold Voltage vs. Virtual Junction Temperature

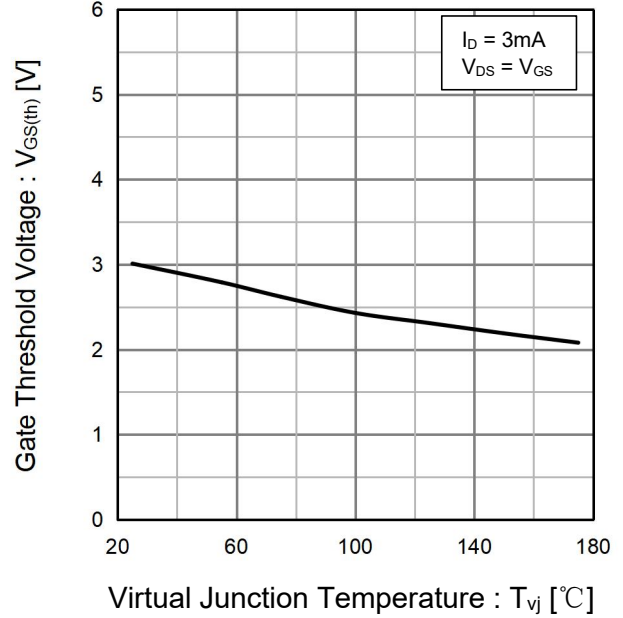


Fig.14 Typical Capacitance vs. Drain - Source Voltage

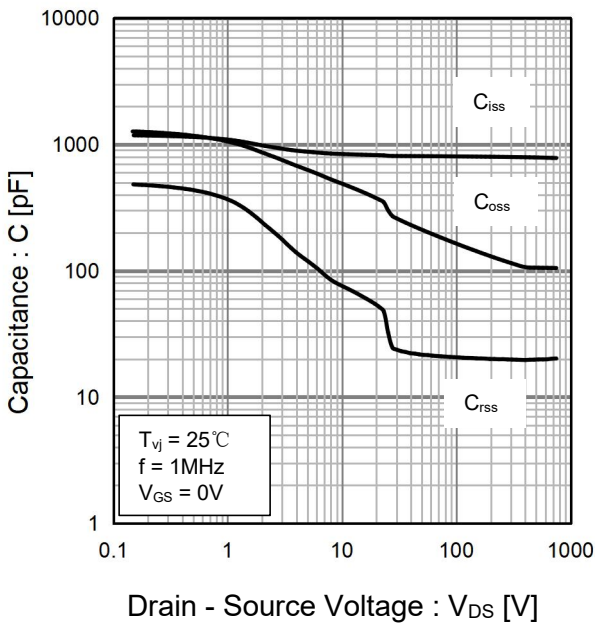


Fig.15 Coss Stored Energy

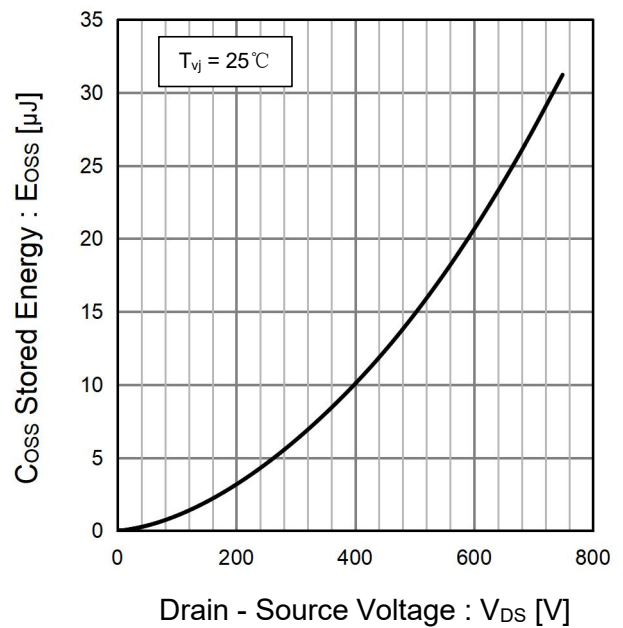


Fig.16 Dynamic Input Characteristics

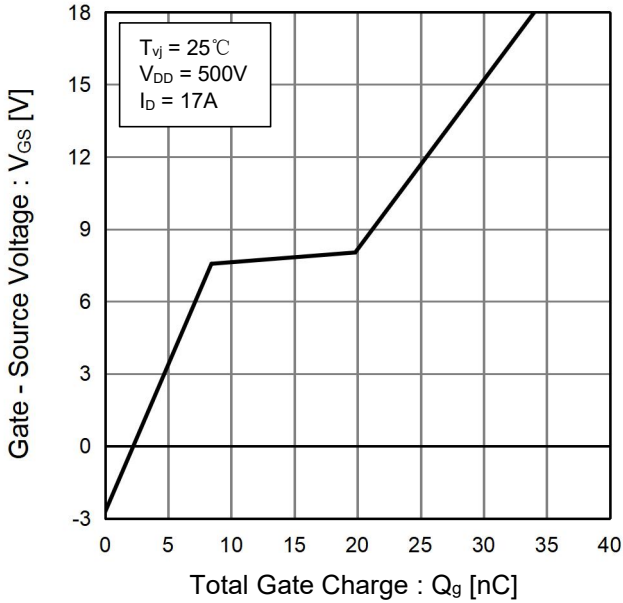


Fig.17 Typical Switching Time vs. External Gate Resistance

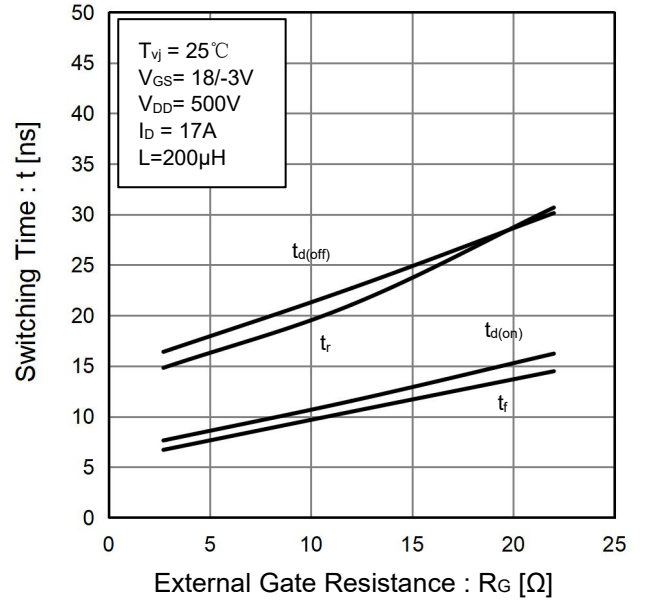


Fig.18 Typical Switching Energy vs. External Gate Resistance

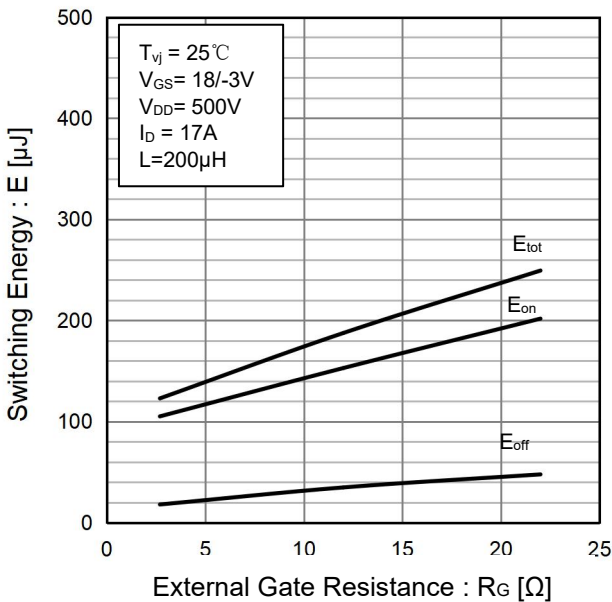


Fig.19 Typical Switching Energy vs. Drain Current

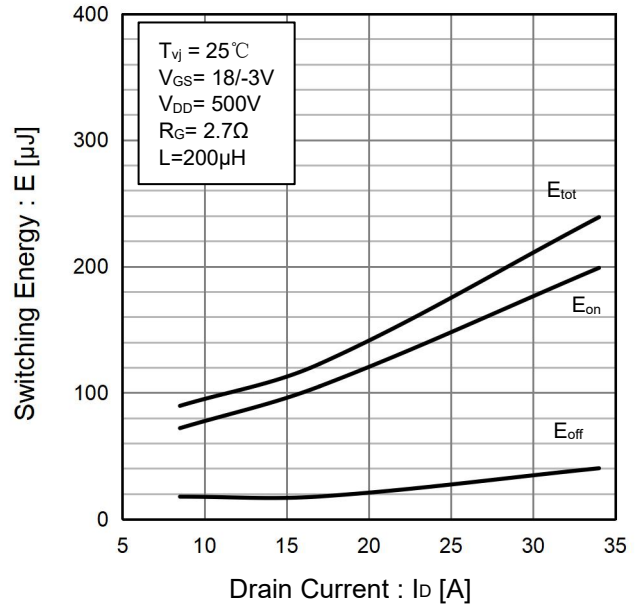
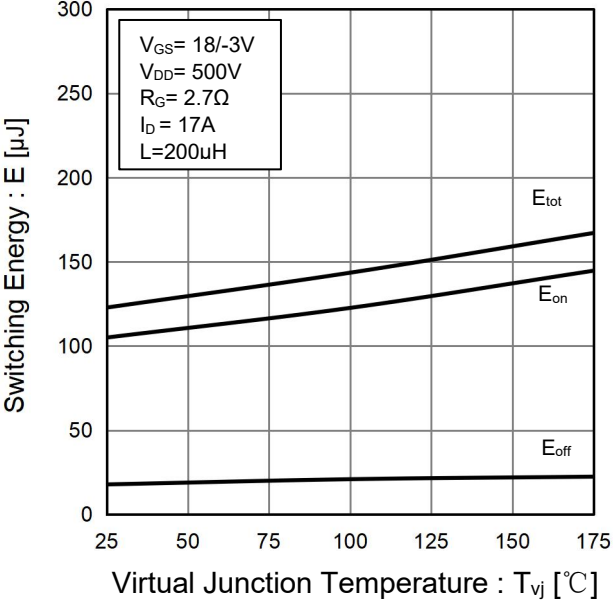
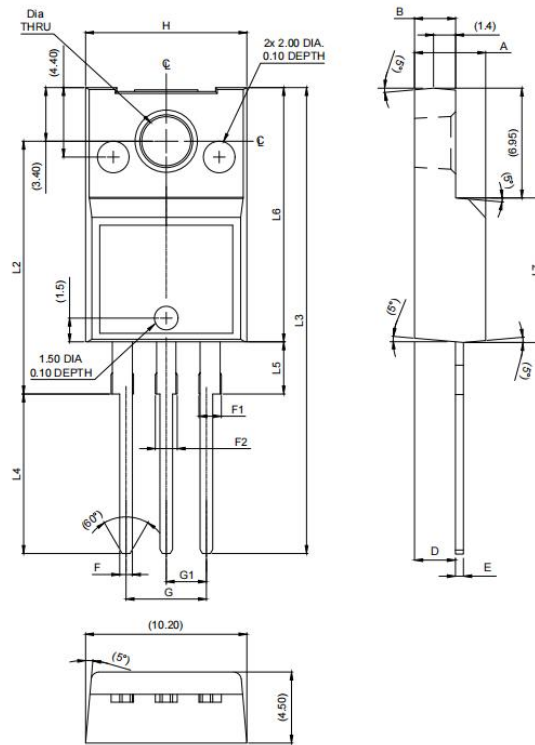


Fig.20 Typical Switching Energy vs. Virtual Junction Temperature



## TO-220F-3L-B Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
B	2.50	2.70	0.098	0.106
D	2.50	2.75	0.098	0.108
E	0.45	0.70	0.018	0.028
F	0.75	1.00	0.029	0.039
F1	1.15	1.50	0.045	0.059
F2	1.15	1.50	0.045	0.059
G	4.95	5.20	0.19	0.20
G1	2.40	2.70	0.09	0.11
H	10.00	10.40	0.39	0.41
L2	16.00		0.63	
L3	28.60	30.60	1.12	1.20
L4	9.80	10.60	0.39	0.42
L5	2.90	3.60	0.11	0.14
L6	15.90	16.40	0.62	0.64
L7	9.00	9.30	0.35	0.37
Dia	3.00	3.20	0.12	0.13

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